

Ball / Land Grid Array Sockets

Screw Lock Type

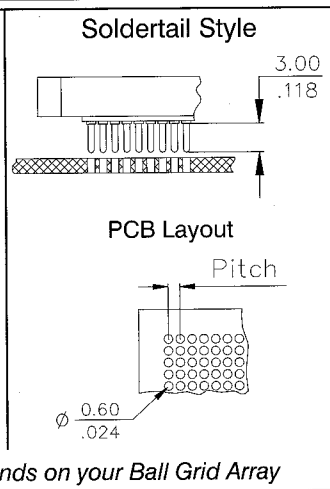
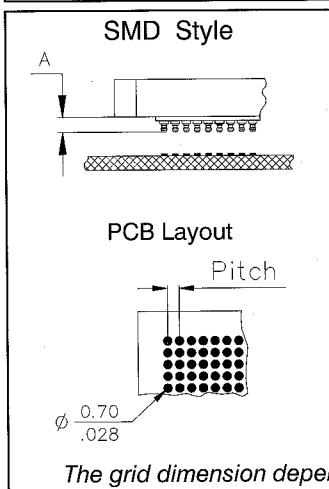
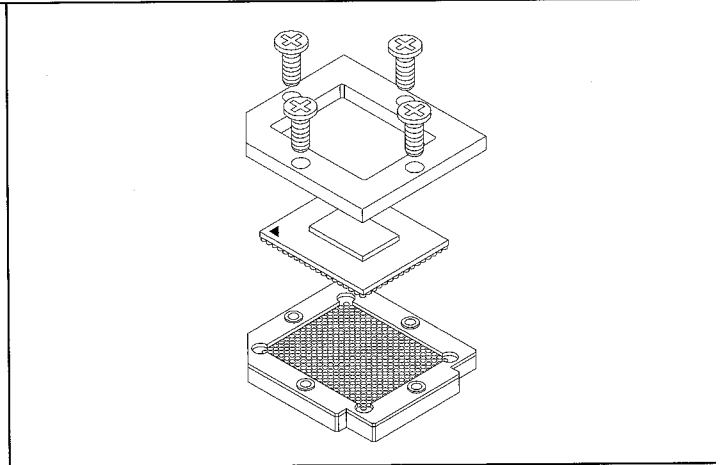
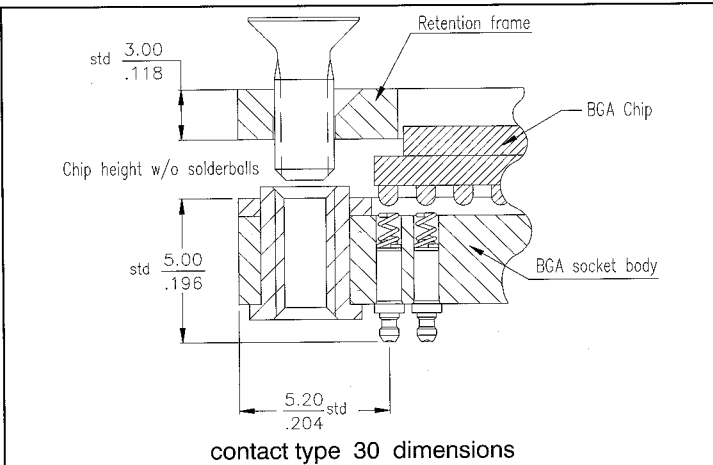
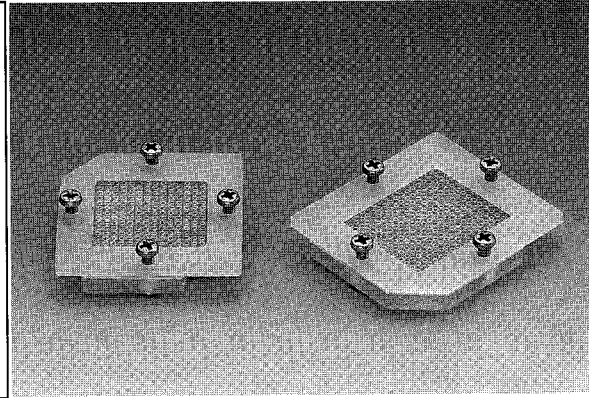
(patents pending)



E-tec is now the leading BGA socket manufacturer.

Sockets range from 5x5 to 33x33 (1089) contacts with even larger parts currently in design. Some of the existing patterns are shown on the following pages, many more exist and your exact requirements can easily be added to our extensive product library. The SMD socket is simply placed and reflowed onto the PCB in the same way as the chip and occupies only a small amount of additional board space. The screw lock socket extends ≈ 5,20 mm beyond the outer ballrow with no fixing holes. We aim to solve your requirements - many different terminals and configurations are available. Your custom sets our standards!

Please note, we will always request the chip data to ensure we offer a compatible socket.



The grid dimension depends on your Ball Grid Array

Specifications	
Mechanical data	
Contact life	min. 100 cycles
Solderability	exceeds MIL-STD-202 Method 208
Individual contact force	40 grams
Max. torque for retention screws	7cN per meter, or 10oz per inch
Material	
Insulator	Glass Epoxy FR 4
Terminal	Brass
Contact	BeCu
Electrical data	
Contact resistance	10 mΩ typical
Current rating	1 A max.
Insulation resistance at 500V DC	> 10 ⁴ MΩ
Breakdown voltage at 60 Hz	1 KV min.
Operating temperature	-55°C to +150°C ; 220°C for 10 sec.

How to order

X X W x x x x - x x x x - x x x x x x (X) ← Options

Device Type B = Ball Grid L = Land Grid C = Column Grid	Device Material C = Ceramic - standard 0,90mm balls P = Plastic - standard 0,60mm balls	Pitch 10 = 1,00mm 12 = 1,27mm 15 = 1,50mm 20 = 2,00mm	Grid Code <i>please refer to the footprint pages</i>	Config Code <i>will be given by the factory after receipt of the chip datasheet</i>	Plating 00 = tin/tin 04 = tin/gold
Socket Locking Type W = screw lock & FR4 solder type body		Nbr of contacts <i>refer to the next pages</i>	Contact Type 30 = standard SMD („A“ = 0,70/.027) 29 = raised SMD („A“ = 4,50/.177) 70 = solder tail		